

B' corners of the semiconductor element, said adhesive lines being adapted for use as a reference for determining a correct placement of the semiconductor element within the area of the circuit forming surface, said adhesive lines adhering said semiconductor element to the circuit forming surface of said semiconductor substrate; and a sealing resin that seals said semiconductor element.

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REMARKS

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The Examiner's Action mailed on November 18, 2002 has been received and its contents carefully considered.

Additionally attached to this Amendment is a Request for Continued Examination (RCE), which is being submitted to ensure consideration and entry of the Amendment to claim 1.

In this Amendment, claim 1 has been amended. Claim 1 is the independent claim. Claims 1 and 19 remain pending in the application, although it is noted that claim 19 has been withdrawn from further consideration. For at least the following reasons, it is submitted that this application is in condition for allowance.

The Examiner has rejected claim 1 as being anticipated by *Sono et al.* (USP 5,920,117). It is submitted that this claim is patentably distinguishable over the cited reference for at least the following reasons.

Applicant's independent claim 1 is directed to a semiconductor device which includes a semiconductor substrate having a circuit forming surface. A plurality of electrode pads are provided on the circuit forming surface. A semiconductor element is mounted on a circuit forming surface. A plurality of adhesive lines which are adapted